

WHAT IS CLAIMED IS:

Sub D1
~~1. An active matrix liquid crystal display comprising:~~

~~a plurality of pixel TFTs arranged in rows and columns on a TFT substrate and arrayed in a matrix;~~

~~driver TFTs formed on said TFT substrate and forming a driver circuit for driving said pixel TFTs;~~

~~a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;~~

~~a counter substrate located opposite to said TFT substrate;~~

~~said TFT substrate having at least one end surface which is cut together with said counter substrate at a common position to thereby form cut surfaces; and~~

~~a nonconductive or weakly conductive material applied or adhesively bonded to at least one of said cut surfaces.~~

Sub D1
~~2. The display of claim 1, wherein said at least one cut surface to which said nonconductive or weakly conductive material is applied or adhesively bonded is parallel or vertical to a direction of array of said pixel TFTs.~~

~~3. The display of claim 1, wherein a control circuit for controlling said driver circuit made up of said driver TFTs is packed on said TFT substrate, and wherein said control circuit is sealed in a sealant material that seals said liquid crystal material.~~

Sub D2
~~4. The display of claim 1, wherein in order to install a control circuit for controlling said driver circuit made up of said driver TFTs in a control circuit accommodation portion of said TFT substrate, said control circuit accommodation portion is~~

made thinner than other portions of said TFT substrate.

5. The display of claim 1, wherein in order to install a control circuit for controlling said driver circuit made up of said driver TFTs in a control circuit accommodation portion of said TFT substrate, said counter substrate has a thinned portion located opposite to said control circuit accommodation portion.

6. The display of claim 3, wherein said control circuit is packed on said TFT substrate by COG (chip-on-glass) technology.

7. The display of claim 4, wherein said control circuit is packed on said TFT substrate by COG (chip-on-glass) technology.

8. The display of claim 5, wherein said control circuit is packed on said TFT substrate by COG (chip-on-glass) technology.

9. A method of fabricating an active matrix liquid crystal display having a plurality of pixel TFTs arranged in rows and columns on a TFT substrate and arrayed in a matrix, driver TFTs formed on said TFT substrate and forming a driver circuit for driving said pixel TFTs, a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film, and a counter substrate located opposite to said TFT substrate, said method comprising the steps of:

cutting at least one end surface of said TFT substrate and said counter substrate at a common position to thereby form cut end surfaces; and

applying or adhesively bonding a nonconductive or weakly conductive material to at least one of said cut end surfaces.

Sub D3
10. The method of claim 9, wherein said cutting step is carried out in such a way that said cut end surfaces to which said nonconductive or weakly conductive material is applied or adhesively bonded are parallel or vertical to a direction of array of said pixel TFTs.

11. The method of claim 9, further comprising the step of sealing a control circuit for controlling said driver circuit made up of said driver TFTs in a sealant material positioned between said substrates.

Sub D4
12. The method of claim 9, further comprising the step of thinning a region of said TFT substrate where a control circuit for controlling said driver circuit made up of said driver TFTs can be installed, in order to install said control circuit.

13. The method of claim 9, further comprising the step of thinning a portion of said counter substrate which is located opposite to a control circuit for controlling said driver circuit made up of said driver TFTs, to install said control circuit.

14. The method of claim 11, wherein said control circuit is packed on said TFT substrate by COG (chip-on-glass) technology.

15. The method of claim 12, wherein said control circuit is packed on said TFT substrate by COG (chip-on-glass) technology.

16. The method of claim 13, wherein said control circuit is packed on said TFT substrate by COG (chip-on-glass) technology.

Add D6

add E3

add F3 14